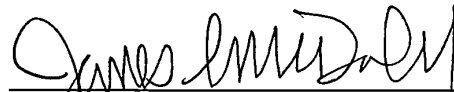


CONCLUSION

Applicant estimates that no fee is due in connection with this Amendment because it is being submitted, under 37 C.F.R. § 1.115, concurrently with filing of the application. However, should the Patent Office determine otherwise, The Commissioner is hereby authorized to charge any fees associated with filing this Amendment to Pennie & Edmonds LLP Deposit Account No. 16-1150. A copy of this sheet is enclosed.

Respectfully submitted,

Date: December 4, 2001



James S. McDonald (Reg. No. 44,229)
For Victor N. Balancia (Reg. No. 31,231)

PENNIE & EDMONDS LLP

1155 Avenue of the Americas
New York, N.Y. 10036-2711
(212) 790-9090

**APPENDIX A:
CHANGES TO SPECIFICATION UPON ENTRY
OF THE PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.115
FILED DECEMBER 4, 2001**

**U.S. PATENT APPLICATION DIVISIONAL OF SERIAL NO. 09/343,532
(ATTORNEY DOCKET NO. 8317-123-999)**

The title beginning at page 1, lines 1-2 is revised as follows:

**POST ETCH CLEANING COMPOSITION ~~AND PROCESS~~ FOR DUAL
DAMASCENE SYSTEM**

**APPENDIX B:
CHANGES TO CLAIMS UPON ENTRY
OF THE PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.115
FILED DECEMBER 4, 2001**

**U.S. PATENT APPLICATION DIVISIONAL OF SERIAL NO. 09/343,532
(ATTORNEY DOCKET NO. 8317-123-999)**

1. (Amended) A composition for removal of etch residues from integrated circuits using copper materials, which comprises a choline compound, water and an organic solvent.

**APPENDIX C:
CLAIMS AS PENDING UPON ENTRY
OF THE PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.115
FILED DECEMBER 4, 2001**

**U.S. PATENT APPLICATION DIVISIONAL OF SERIAL NO. 09/343,532
(ATTORNEY DOCKET NO. 8317-123-999)**

1. (Amended) A composition for removal of etch residues from integrated circuits using copper materials, which comprises a choline compound, water and an organic solvent.
2. The composition of claim 1 in which the composition from about 10 percent by weight to about 50 percent by weight of the choline compound.
3. The composition of claim 2 in which the composition comprises from about 10 percent by weight to about 80 percent by weight of the water.
4. The composition of claim 3 in which the composition comprises from about 20 percent by weight to about 80 percent by weight of the organic solvent.
5. The composition of claim 1 in which the choline compound comprises choline hydroxide, choline bicarbonate or choline chloride.
6. The composition of claim 5 in which the choline compound is choline hydroxide.
7. The composition of claim 5 in which the organic solvent comprises propylene glycol, dimethyl sulfoxide, monoethanolamine, or diglycolamine.
8. The composition of claim 1 in which the composition additionally comprises hydroxylamine.
9. The composition of claim 1 in which the composition additionally comprises a corrosion inhibitor.